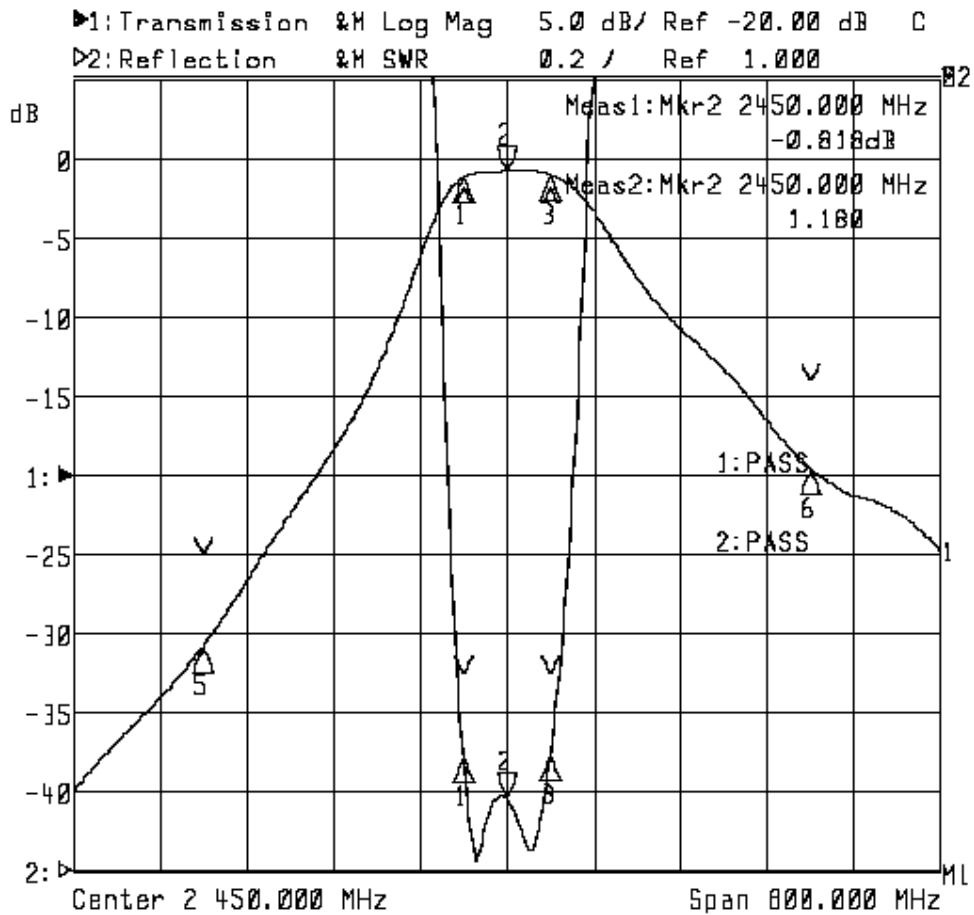


● 电气性能 Electrical Characteristics

表 2

No.	Item (项目)	Specifications (特性)	Post Environmental Tolerance (环境试验后允许附加误差)
5.1	Center frequency 中心频率(f_0)	2450.00 MHz	± 1.5 MHz
5.2	Insertion loss 插入损耗	≤ 2.0	± 0.5 dB
5.3	Band width 通带宽度	$f_0 \pm 40.0$ MHz	± 0.5 MHz
5.4	Ripple (in BW) 通带波动	1.0 dB Max.	± 0.5 dB
5.5	V.S.W.R. (in BW) 驻波比	2.0 Max.	± 0.5
5.6	Attenuation (Absolute value) 阻带衰耗 (绝对值)	15dB min(f_0+280 MHz) 25dB min(f_0-280 MHz)	± 2 dB
5.7	Permissible Input power (Max) 允许最大输入功率	1 Watt	---
5.8	In/output impedance 输入/输出阻抗	50 Ω	---

● 特性曲线 Characteristic curve



● 环境试验 Environmental specifications

经环境试验后允许比起始读数偏差见表 2

Post Environmental Tolerance (Refer to the table 2)

基准条件: 温度范围	Temperature range	25-/+3 °C
相对湿度范围	Relative Humidity range	55~75%RH
工作温度	Operating Temperature range	-10 °C ~+70 °C
贮藏温度	Storage Temperature range	-25 °C ~+85 °C

● 耐湿热特性 Moisture Proof

在温度为 40-/+2 °C, 相对湿度 90~95%的恒温湿箱中放置 96 小时, 在常温中恢复 1~2 小时后测试, 符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature 40-/+2 °C and the relative humidity 90~95% RH for 96 hours and 1~2 hours recovery time under normal condition.

● 耐振动 Vibration Resist

在振动频率为 10~55Hz 振幅为 1.5mm 沿 X.Y.Z 方向各振动 2 小时后测试符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after applied to the vibration of 10 to 55Hz with amplitude of 1.5mm for 2 hours each in X, Y and Z directions.

● 耐跌落冲击 Drop Shock

在 30cm 高度处按 X,Y,Z 三个面分别自由跌落在木制地板上共 3 次后测试符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after dropping onto the hard wooden board from the height of 30cm for 3 times each facet of the 3 dimensions of the device.

● 高温特性 High Temperature Endurance

在温度为 $80\text{--}/+5\text{ }^{\circ}\text{C}$ 的恒温箱中放置 $24\text{--}/+2$ 小时, 在常温中恢复 1~2 小时后测试. 符合表 5.1~5.6 规定.

The device should satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to temperature $80\text{--}/+5\text{ }^{\circ}\text{C}$ for $24\text{--}/+2$ hours and 1~2 hours recovery time under normal temperature.

● 低温特性 Low Temperature Endurance

在温度为 $-25\text{ }^{\circ}\text{C--}/+3\text{ }^{\circ}\text{C}$ 低温箱中放置 $24\text{--}/+2$ 小时后恢复 1~2 小时测试符合表 5.1~5.6 规定.

The device should also satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the temperature $-25\text{ }^{\circ}\text{C--}/+3\text{ }^{\circ}\text{C}$ for $24\text{--}/+2$ hours and to 2 hours recovery time under normal temperature.

● 温度循环 Temperature Cycle Test

在 $-25\text{ }^{\circ}\text{C}$ 温度中保持 30 分钟, 再在 $+85\text{ }^{\circ}\text{C}$ 温度中保持 30 分钟, 共循环 5 次后在常温中恢复 1~2 小时后测试符合表 5.1~5.6 规定.

The device should also satisfy the electrical characteristics specified in paragraph 5.1~5.6 after exposed to the low temperature $-25\text{ }^{\circ}\text{C}$ and high temperature $+85\text{ }^{\circ}\text{C}$ for $30\text{--}/+2$ min each by 5 cycles and 1 to 2 hours recovery time under normal temperature.

● 耐焊接热 Solder Heat Proof

能承受经 $120\text{--}150\text{ }^{\circ}\text{C}$ 的温度预热 60 秒后 在 $260\text{ }^{\circ}\text{C} +10\text{ }^{\circ}\text{C}$ 的焊锡浸 $10\text{--}/+0.5$ 秒.

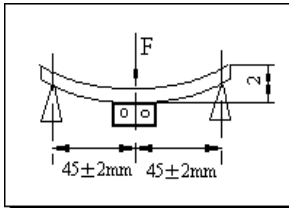
The device should be satisfied after preheating at $120\text{ }^{\circ}\text{C} \sim 150\text{ }^{\circ}\text{C}$ for 60 seconds and dipping in soldering Sn at $260\text{ }^{\circ}\text{C} +10\text{ }^{\circ}\text{C}$ for $10\text{--}/+0.5$ seconds.

● 结合力试验 Tensile Strength of Terminal

在产品电极端子上或表面上应能承受 1kg 垂直拉力 $10\text{--}/+1$ 秒.

The device should not be broken after tensile force of 1.0kg is slowly applied to pull a lead pin of the fixed device in the lead axis direction for 10-/+1 seconds.

● 耐弯曲试验 Bending Resist Test



将产品按图焊在 1.6-/+0.2mm 的 PCB 板中间, 由箭头方向施力: 1mm/S, 弯曲距离: 2mm, 保持 5-/+1S, 产品金属层无脱落.

Weld the product to the center part of the PCB with the thickness 1.6-/+0.2mm as the illustration shows, and keep exerting force arrow-ward on it at speed of : 1mm/S , and hold for 5-/+1S at the position of 2mm bending distance , so far , any peeling off of the product metal coating should not be detected .

● 回流焊温度 Reflow Soldering Standard Condision

